COMPONENT SPECIFICATION

版次:第5.0版 MAX ECHO

Name	Ferrite Chip EMI Suppressors	COMPOSITE SPECIFICATION		1/
	ACMS-321611	SPEC#	ACMS321611A501 2.5A	/ 8

1. Scope

This specification applies to the ACMS-3216 series Ferrite Chip EMI suppressors.

2. Standard and Atmospheric Conditions

Unless otherwise specified the standard range of atmospheric conditions for making measurements and tests is as follows:

Ambient temperature : 20±15°C Relative humidity : 30~70%

If there may be any doubt on the results, measurements shall be made within

the following limits:

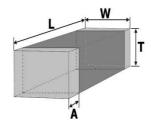
Ambient temperature : 25±5°C Relative humidity : 30~70%

3. Ratings

			*
PART NO	IMPEDANCE (Ω)	DC RESISTANCE	RATED CURRENT
	AT100 MHz 500mV	(Ω) Max	(mA) Max
ACMS321611A501 2.5A	500±25%	0.07	2500

[%]The maximum rated current : the DC current value having temperature increased 40 $^{\circ}$ C after thru DC current 2 hours at ambient temperature.

4. Dimensions



unit: mm (inch) OPERATING TEMP. RANGE : -55° C ~ $+125^{\circ}$ C STORAGE TEMP. RANGE : -40° C ~ $+85^{\circ}$ C

			- 0	0
TYPE	Ш	W	Т	Α
ACMS-3216	3.2±0.2	1.6±0.2	1.1±0.2	0.4~1
7.010.0 02.10	(0.126±0.008)	(0.063±0.008)	(0.043±0.008)	(0.016~0.039)

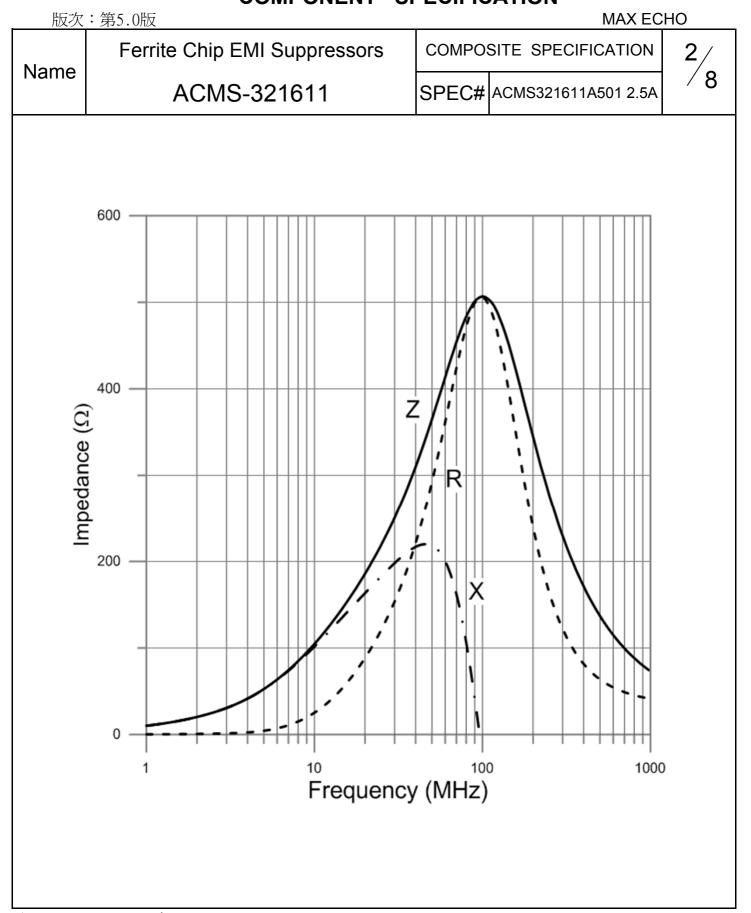
5. The Place of Origin:

Taichung, Taiwan

PLANNED BY	CHECKED BY	APPROVED BY	
LUN	TINA	Chi Chi Huang	鈺鎧文件中心 發行章

表格編號:034承認書 A 2016/8/22

MAX ECHO 鈺鎧科技股份有限公司規格標準書 COMPONENT SPECIFICATION



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Name

Ferrite Chip EMI Suppressors ACMS-321611

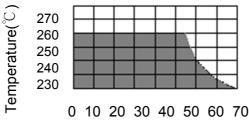
COMPOSITE SPECIFICATION

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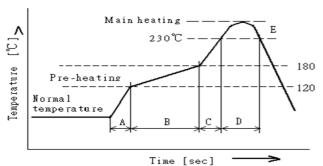
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6. Reflow soldering conditions

- Pre—heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max.
 Insufficient pre—heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Products should be soldered within the following allowable range indicated by the slanted line. The excessive soldering conditions may cause the corrosion of the electrode, when soldering is repeated, allowable time is the accumulated time.



Temperature Profile



A	Slope of temp. rise	1 to 5	°C/sec
D	Heat time	50 to 150	sec
В	Heat temperature	120 to 180	$^{\circ}\mathbb{C}$
C	Slope of temp. rise	1 to 5	°C/sec
D	Time over 230°C	90~120	sec
Е	Peak temperature	255~260	$^{\circ}\mathbb{C}$
Ľ	Peak hold time	10 max.	sec
No. of mounting		3	times

(Melting area of solder)

6-1 Reworking with soldering iron

Preheating	150°ℂ, 1 minute
Tip temperature	280°C max.
Soldering time	3 seconds max.
Soldering iron output	30w max.
End of soldering iron	φ 3mm max.

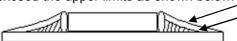
Reworking should be limited to only one time.

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

6-2 Solder Volume

Solder shall be used not to be exceed the upper limits as shown below.

Upper Limit
Recommendable



Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

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7. Equipment

7-1 IMPEDANCE

Impedance shall be measured with HP-4286A impedance analyzer or equivalent system

7-2 DC RESISTANCE

DC resistance shall be measured using HP 4338 digital mili—ohm meter with 4 terminal method.

8. Mechanical Characteristics

8. Mechanical Characteristics				
ITEM	Specification	Test Conditions		
Terminal	Terminal strength does not distort	Solder chip on PCB and applied 10N		
Strength		(1.02Kgf) for 10 sec		
	resistance specifications.	CHIP		
		Oksia Apone PCB		
Substrate	SPEC substrate bending test DC	After soldering a chip to a test substrate,		
Bending Test	resistance shall meet	bend the substrate by 3mm hold for 10s		
	specifications.	and then return.		
		Soldering shall be done in accordance with the recommended PC board pattern		
		and reflow soldering.		
		unit:mm 45 45 45 100		
Resistance	No visible damage	Solder Temp. : 265±3℃		
to Solder Heat	mechanical characteristics shall be satisfied.	Immersion time : 6±1 sec		
		Preheating : 100° C to 150° C, 1 minute.		
		Measurement to be made after keeping at room		
	Consult standard MIL-STD-202	temp for 24±2 hrs.		
	METHOD 210	Solder : Sn-3Ag-0.5Cu		
Solderability	95% min. coverage of all	Solder temp. : 240 ± 5 $^{\circ}$ C		
	metabolised area	Immersion time: 3±1 sec		
		Solder : Sn-3Ag-0.5Cu		
	Consult standard J-STD-002			

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- 9. RELIABILITY AND TEST CONDITIONS 9-1 HIGH TEMPERATURE RESISTANCE
 - - a. Performance specification
 - 1.Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs
 - 3.Measurement: After placing at room ambient temperature for 24 hours minimum
 - 9-2 Biased Humidity RESISTANCE
 - a.Performance specification
 - 1. Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.Humidity: 85 ± 5%RH

 - 2. Temperature: 85°C ±2°C
 3.Testing time: 1000 ± 12 hours
 4.Measurement: After placing at room ambient temperature for 24 hours minimum
 - 9-3 TEMPERATURE CYCLE
 - a.Performance specification
 - 1.Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1. Low Temperature: 55°C ±5°C kept stabilized for 30 minutes each 2. High Temperature: 125°C ±5°C kept stabilized for 30 minutes each

 - 2.Cycle: 1000 cycles
 - 3. Measurement: After placing for 24hours minimum at room ambient temperature
 - 4. step1. -55°C temp±5°C 30±3 minutes step2. Room temperature 2to5 minutes
 - 9-4 VIBRATION TEST
 - a.Performance specification

 - 1.Appearance: no mechanical damage
 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.Frequency and Amplitude:10-2000-10Hz
 - 2.Direction:X,Y,Z.
 - 3.Test duration:4 hours for each direction,12hours in total.
 - 9-5 Mechanical Shock TEST
 - a.Performance specification
 - 1.Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.peak acceleration : 100 g's
 - 2.Duration of pulse: 6 ms
 - 3. Waveform : Half-sine

 - 4.Velocity change : 12.3 ft/sec 5. Direction : X , Y , Z (3axes/3 times)
 - 9-6 Operational Life
 - a. Performance specification
 - 1.Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.Temperature: 125°C ±2°C 2.Testing time: 1000±12hrs
 - 3.Measurement: After placing at room ambient temperature for 24 hours minimum
 - 9-7 Electrostatic discharge test
 - a. Performance specification
 - 1.Appearance: no mechanical damage
 - 2. Impedance shall be with ±30% of the initial value
 - b.Test condition
 - 1.ESD voltage: 15k volts
 - 2.Mode 1:150 pF/330 Ohm
 - 3.Mode 2:150 pF/2000 Ohm

The reliability test customers if there are special requirements in accordance with customer needs

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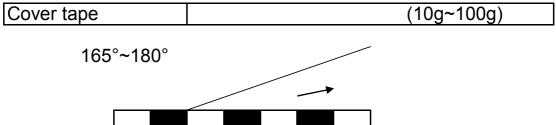
版次:第5.0版 **MAX ECHO** Ferrite Chip EMI Suppressors **COMPOSITE SPECIFICATION** 6 Name ACMS-321611 SPEC# ACMS321611A501 2.5A EMBOSSED CARRIER TAPE PACKING 10-1 DIMENSIONS Unreeling direction B0 A0 P2 P0 D0 D1 0.22 1.88 3.5 1.75 2.00 1.55 1.00 1.49 ±0.05 ±0.1 | ±0.05 | ±0.1 ±0.1 ±0.2 ±0.1 ±0.1 ±0.05 ±0.1 ±0.15 ±0.05 ±0.25 10-2 LEADER AND TRAILER TAPE Trailer Components Empty compar tments Leader End Start 110mm of more H.₩ 10-3 DIRECTION THE DIRECTION SHALL BE SEEN FROM THE TOP OF COVER TAPE Unreeling direction 10-4 REELS UNIT:mm 178 ±2.0 .0±0.5 50 MIN 10 20 PACKING QTY. 3,000 PCS REEL

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10-5 PEELING STRENGTH OF COVER TAPE



Test condition

1. peel angle: 165°~180° vs carrier tape

2. peel speed: 300mm/min

11. Packaging

- 1. Tape & Reel packaging in composite specification 6/8
- 2) Reel and a bag of desiccant shall be packed in Nylon or plastic bag
- 3) Maximum of 5 reels shall be packaged in a inner box
- 4) Maximum of 6 inner box shall be packaged in a outer box

12. Reel Label

Producing the goods label needs to indicate (1) Pb Free (2) RoHS Compliant

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13. Storage

- 13-1The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to high humidity. Packages must be stored at 40°C or less and 70% RH or less.
- 13-2 The solderability of the external electrode may be deteriorated if packages are stored where they are exposed to dust or harmful gas (hydrogen chloride, sulfurous acid gas or hydrogen sulfide).
- 13-3 Packaging material may be deformed if packages are stored where they are exposed to heat or direct sun—light.
- 13-4 Minimum packages, such as polyvinyl heat—seal packages shall not be opened until just before they are used.

 If opened, use the reels as soon as possible.
- 13-5 Solderability specified in composite specification 4/8 shall be for 6 months from the date of delivery on condition that they are stored at the environment specified clause 13-1 & 13-2.

For those parts which passed more than 6 months shall be checked solderability before it is used.

14. Quality System

- ISO/TS16949
- IECQ QC 080000